

3D

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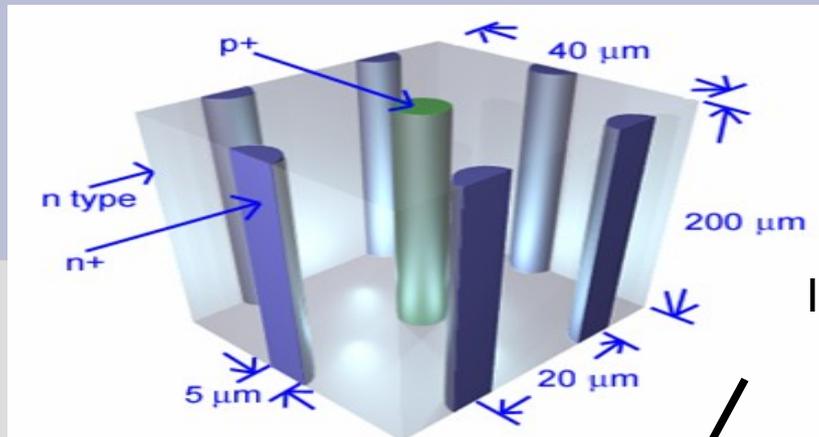
- Efficiencies

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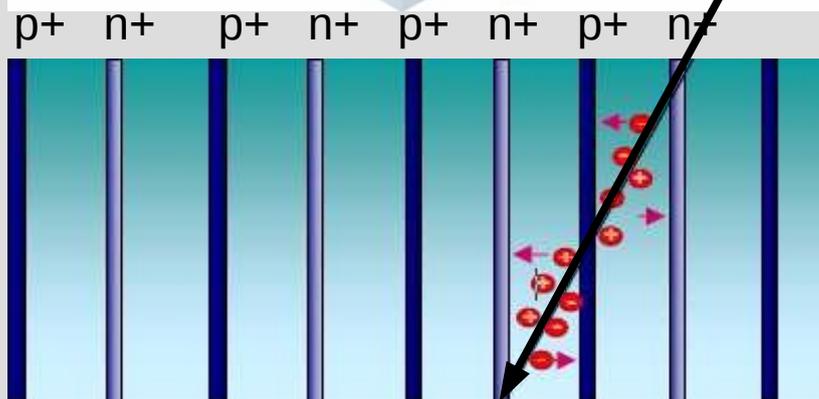
2009 testbeam

3D-setup at detector-lab in Bergen

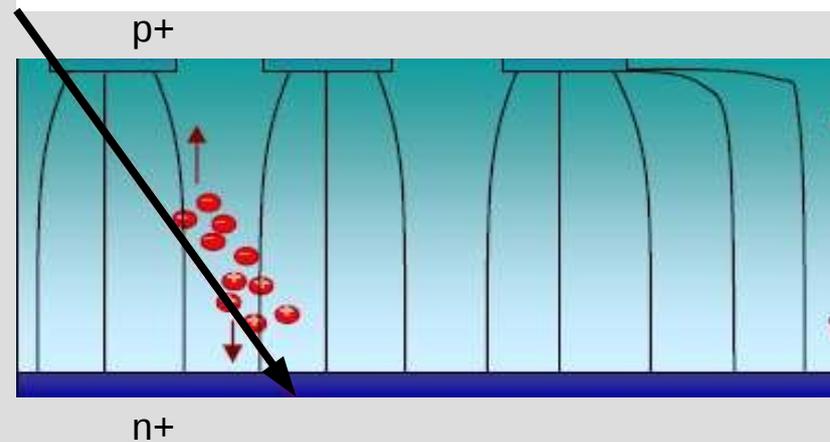
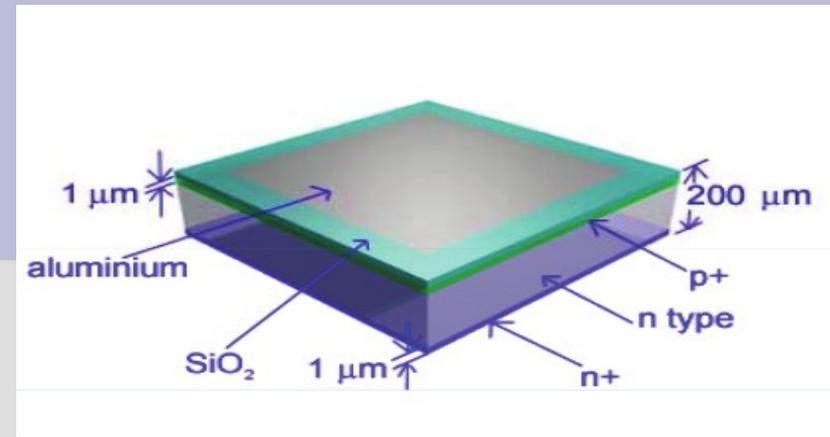
3D : The electrodes are fabricated inside the silicon bulk



Incoming charged particle



Planar: Electrodes implanted on wafer surfaces



Short inter-electrode distance

- **Faster signal** (a few ns time-resolution)
- **Radiation hard** (Smaller trapping probability after irradiation)

Larger collection area of 3D electrodes than planar implanted electrodes:

- **Low depletion voltage** (electric field higher for any given maximum applied field)

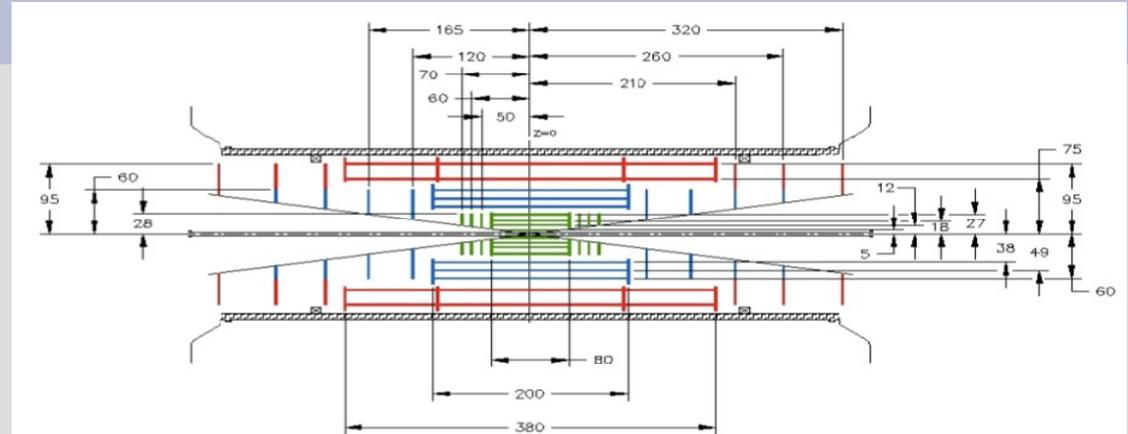
Active edge (Sensors surrounded by an “active edge”-electrode)

- **Less dead area** (a few um)

Why 3D:

Atlas upgrade:

- Radiation hardness a key requirement for the innermost tracker detectors at forward LHC experiments
- Role of reconstructing vertices of very short lived particles demands high efficiency
- Needs to be replaced when performance is significantly degraded.
- LHC upgrade in 2017 to a new peak luminosity of $10^{35} \text{ cm}^{-2}\text{s}^{-1}$ (At this point several detectors will need replacement)
- The B-layer however might need replacement already in 2013 as it is situated only ~4cm from interaction point

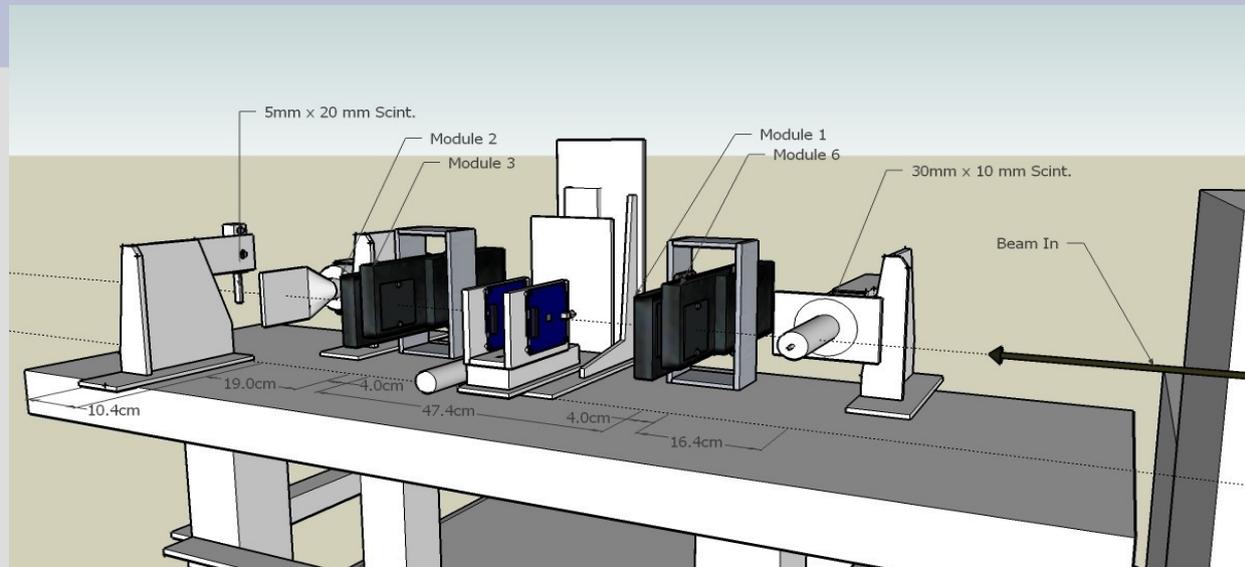


New Inner Detector layout for the ATLAS upgrade :9 layers of silicon detectors, 4 pixel layers (~5 m²), 3 layers of short strips (~60 m²) and 2 layers of long strips (~100 m²).

Medical applications:

- Medical imaging

Testbeam-setup 2008:



180 GeV/s π^{\pm} beam passes through setup.

When scintillators in front and back of sensors are hit, readout of detectors are triggered.

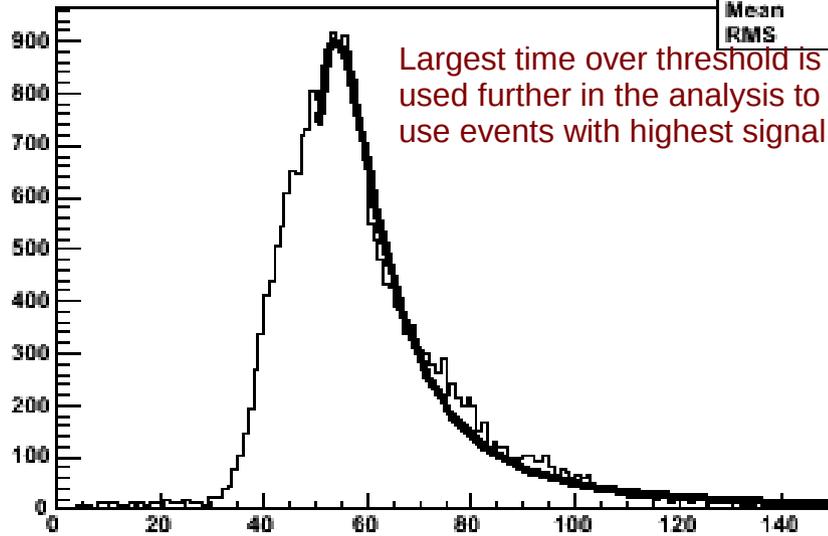
When a particle pass through several pixel layers in a row, track is constructed.

In addition a very well calibrated beam telescope gives “real tracks”

In the analysis we have compared the reconstructed and the real tracks

Time over threshold plots:

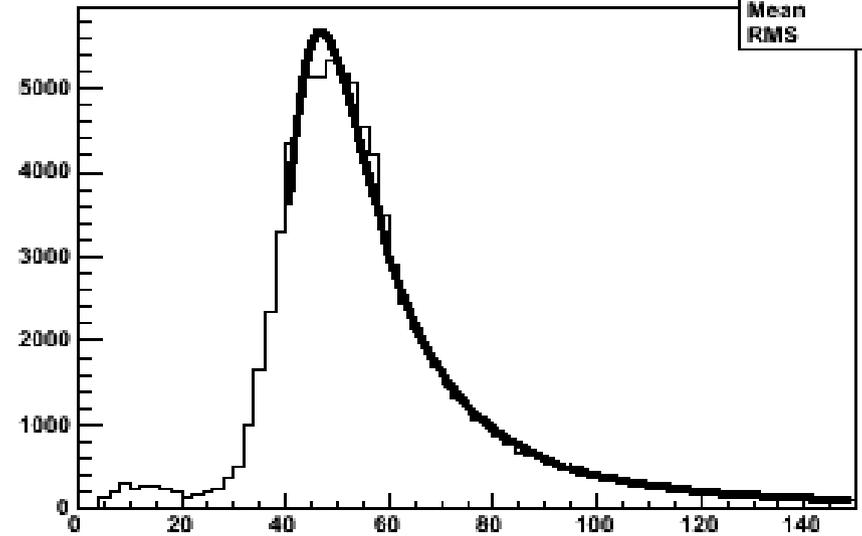
track in pixel



tot1	
Entries	25942
Mean	59.58
RMS	18.22

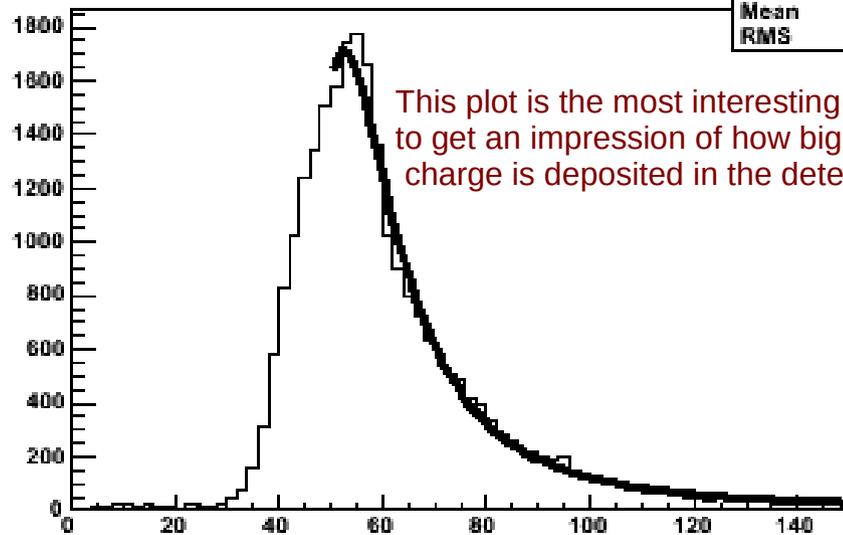
Largest time over threshold is used further in the analysis to use events with highest signal

ToT for pixel with highest ToT and the closest pixels around



totcluster1	
Entries	89549
Mean	57.11
RMS	22.13

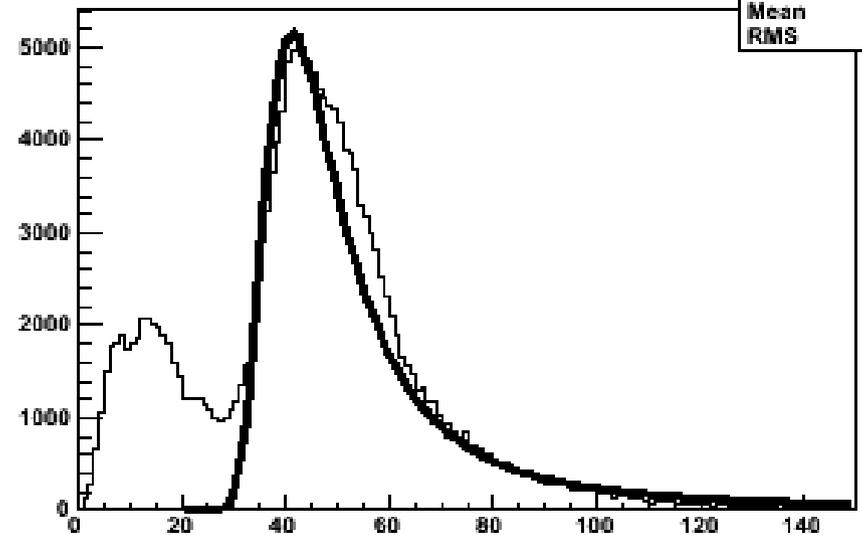
ToT for pixel with highest ToT and the closest pixels around when $abs(xdiff[k]) > 250$ and $abs(ydiff[k]) > 50$



totcluster2	
Entries	25942
Mean	60.88
RMS	20.03

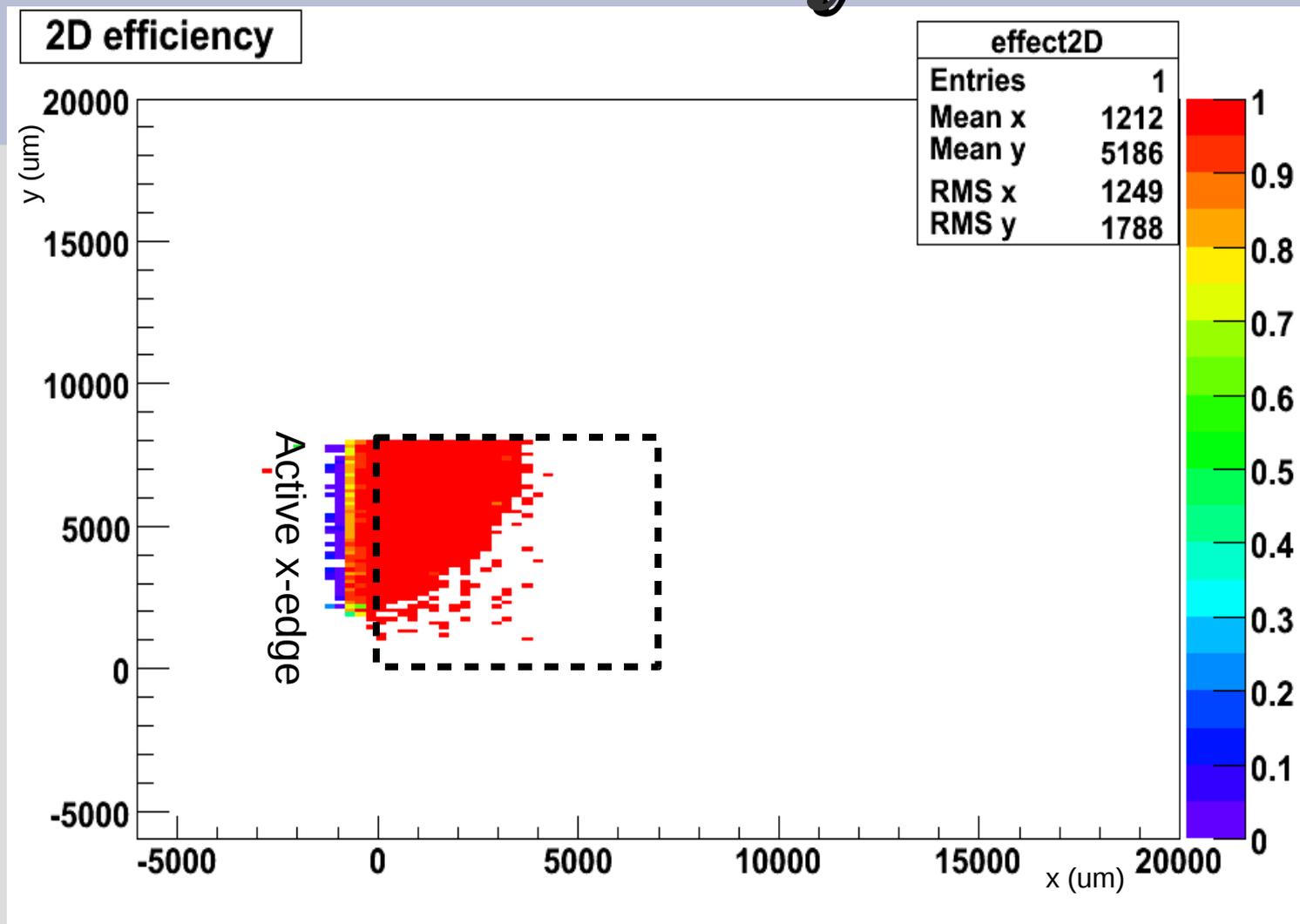
This plot is the most interesting to get an impression of how big charge is deposited in the detector

All ToT



total1	
Entries	179674
Mean	44
RMS	21.85

Efficiency

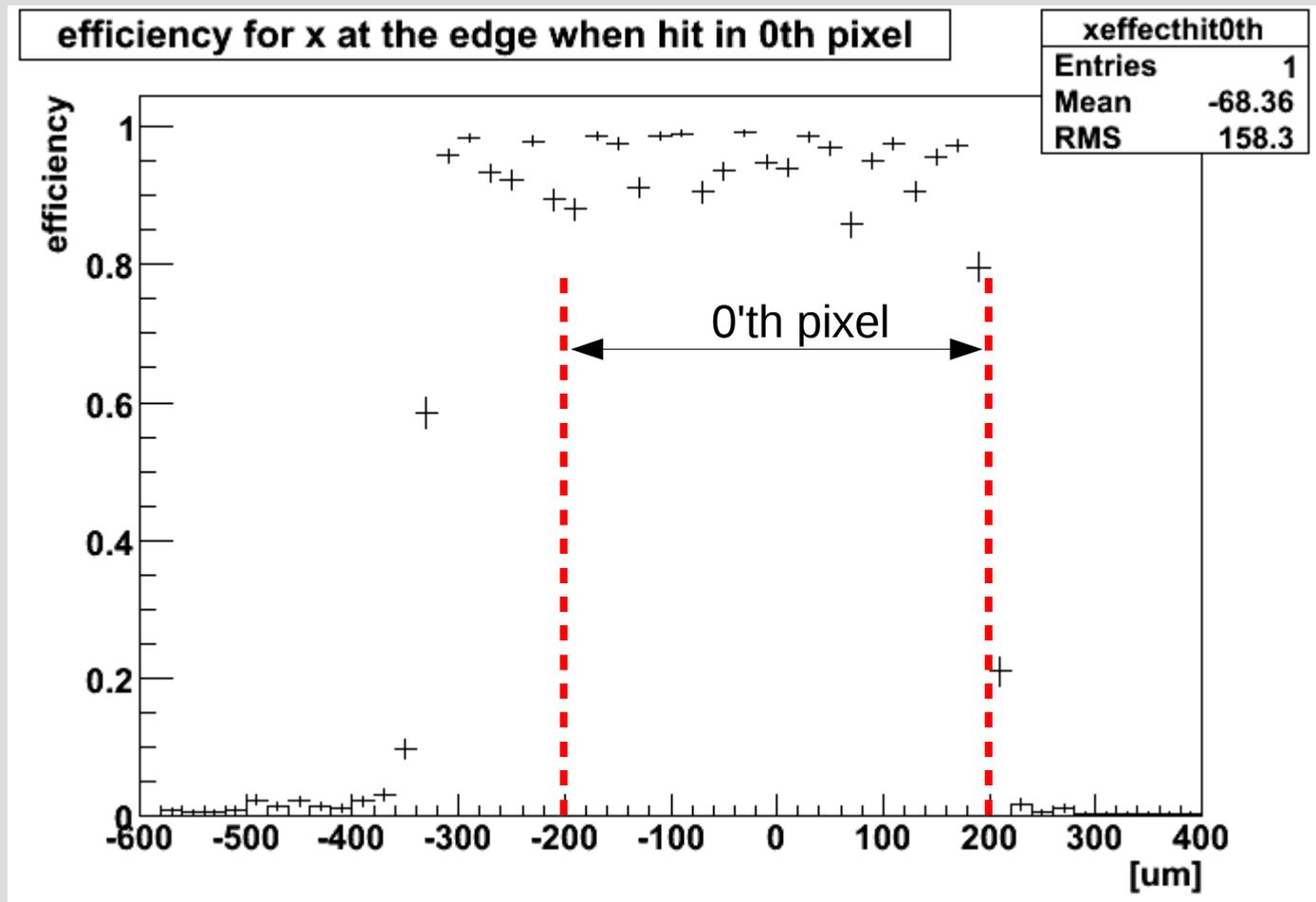


2D efficiency plot shows tracks with registered hits divided on number of real tracks passing

The beam is centered at the detectors edge to study the active edge.

The detector stretches from 0 to 7200um in x direction and from 0 to 8000um in y direction.

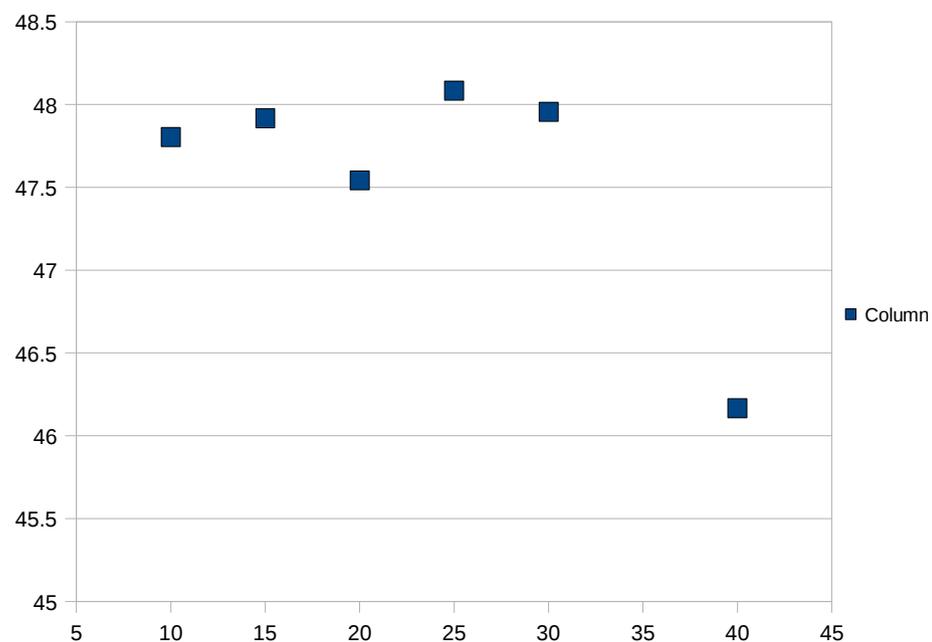
Active edge:



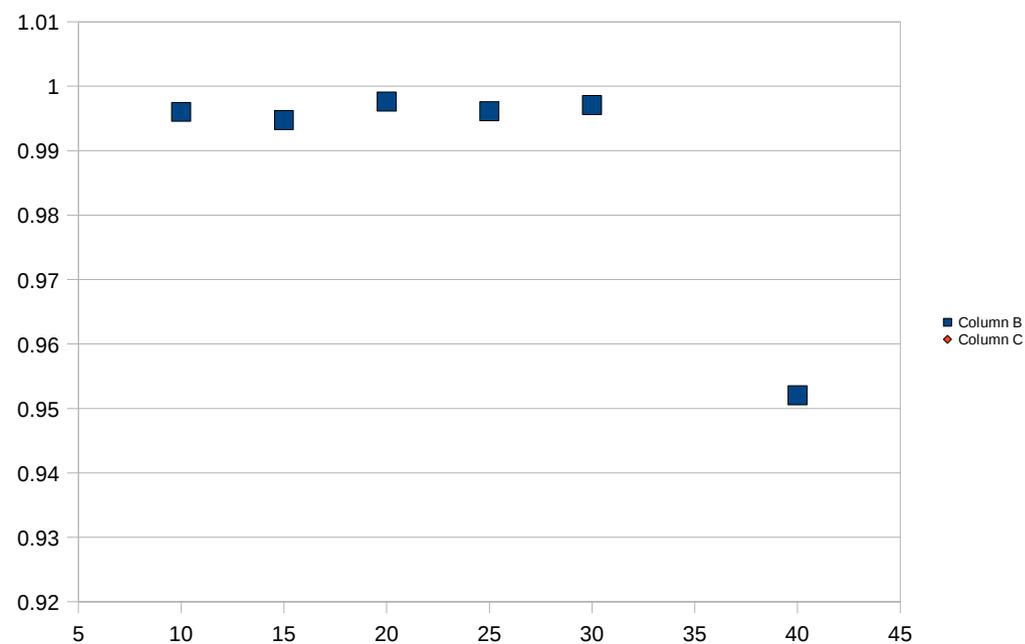
Efficiency when 0th pixel has a registered hit

One can see high efficiency also outside the detector edge at -200um

ClusterToT as a function of bias voltage:



Efficiency as a function of bias voltage:

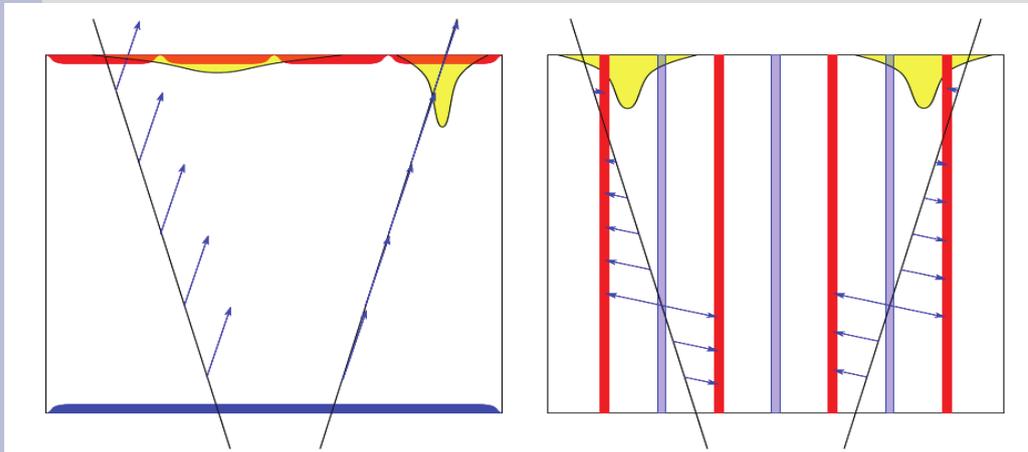


The drop one can see at 40V might be a pre-stage to detector break-down at 50V

2009 Testbeam

Main goal to test the detectors in a magnetic field (1.4T) at various angles

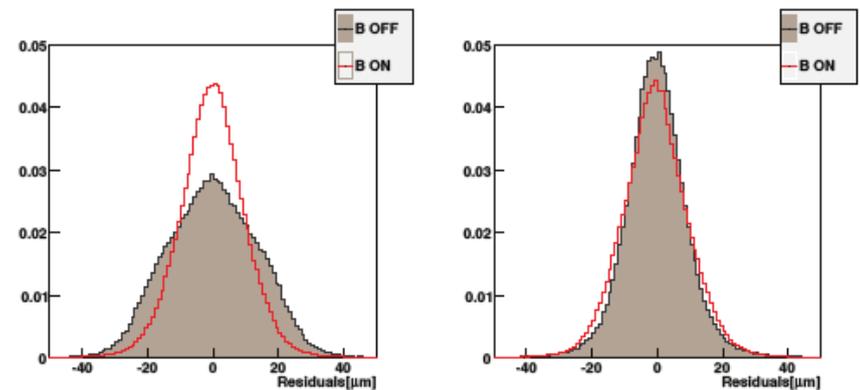
The charge collection in a magnetic field:



Planar: Effect can be focusing and de-focusing

3D: only very small effect

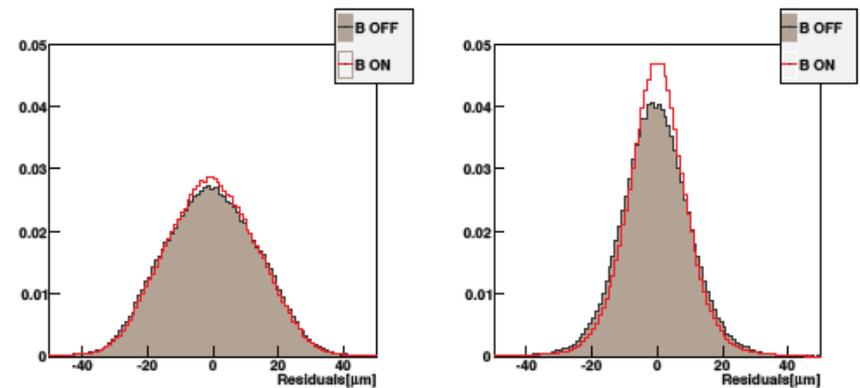
Planar device:



(a) Perpendicular tracks

(b) Inclined tracks

Stanford device:



(c) Perpendicular tracks

(d) Inclined tracks

3D setup in detector -lab

